

# PREFACE

Dear Distinguished Delegates and Guests,

The Organizing Committee warmly welcomes our distinguished delegates and guests to the 2012 2nd International Conference on Management, Manufacturing and Materials Engineering (ICMMM 2012) held on September 21-23, 2012, Beijing, China.

ICMMM 2012 is sponsored by International Association of Management Science and Engineering Technology (IAMSET). The ICMMM 2012 is organized to gather members of our international community scientists so that researchers from around the world can present their leading-edge work, expanding our community's knowledge and insight into the significant challenges currently being addressed their research. The conference Program Committee is itself quite diverse and truly international, with membership from the America, Europe, Asia, Africa and Oceania.

This proceeding records the fully refereed papers presented at the conference. The main goal of these events is to provide international scientific forums for exchange of new ideas in a number of fields that interact in-depth through discussions with their peers around the word. These research area include management engineering, Manufacturing Engineering and Modeling, System Modeling and Simulation, Automation Control and Applications, Materials Science and Engineering, Computer Science and Logistics Engineering, Sensor and the Internet of Things, Computer Science and Logistics Engineering, Engineering and Management, Mechanical Science and Engineering. Most of these papers are inter-discipline research and front studies. All the submitted papers in the proceeding have been peer reviewed by the reviewers drawn from the scientific committee, external reviewers and editorial board depending on the subject matter of the paper. Reviewing and initial selection were undertaken electronically. After the rigorous peer-review process, the summitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The selected papers and additional late-breaking contributors to be presented as lectures will make an existing technical program.

The high quality of the program-guaranteed by the presence of an unparalleled number of internationally recognized top experts can be assessed when reading the contents of the program. The conference will therefore be a unique event, where attendees will be able to appreciate the latest results in their field of expertise, and to acquire additional knowledge in other fields. The program has been structured to favor interactions among attendees coming from many diverse horizons, scientifically, geographically, from academia and from industry. Included in this will to favor interactions are social events at prestigious sites.

We would like to thank the program chairs, organization staff and the members of the program committees for their work. Thanks also go to Advanced Materials Research Journal, for its wonderful editor service to this proceeding.

We are grateful to all those who have contributed to the success of ICMMM 2012. We hope that all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process. Finally, we would like to wish you success in your technical presentations and social networking.

We hope you have a unique, rewarding and enjoyable week at ICMMM 2012 in Beijing, China.

With our warmest regards,

ICMMM 2012 Organizing Committees

September 21-23, 2012,

Beijing, China

# Papers Reviewer

Prof. Dean Vucinic, Vrije Universiteit Brussel, Belgium

Prof. Jinfeng Wang, Zhengzhou University, China

Prof. Dr. Emanuele Habib, University of Rome “La Sapienza”, Italy

Prof. Dr. Huang Xiaoxia, University of Science and Technology Beijing, China

Dr. Mongkol Mongkolwonroj, University of Wisconsin-Madison, Thailand

Dr. Eng. Ahmed Kadhim Hussein, University of Babylon, Babylon City, Hilla, Iraq

Dr. Bai-Da Zhang, National University of Defense Technology, Changsha, Hunan, China

Prof. Wang Jun, Henan University of Technology, China